CMOS MSI

Quad R-S Latches

The MC14043B and MC14044B quad R-S latches are constructed with MOS P-Channel and N-Channel enhancement mode devices in a single monolithic structure. Each latch has an independent Q output and set and reset inputs. The Q outputs are gated through three-state buffers having a common enable input. The outputs are enabled with a logical "1" or high on the enable input; a logical "0" or low disconnects the latch from the Q outputs, resulting in an open circuit at the Q outputs.

Features

- Double Diode Input Protection
- Three-State Outputs with Common Enable
- Outputs Capable of Driving Two Low–power TTL Loads or One Low–Power Schottky TTL Load Over the Rated Temperature Range
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Pb-Free Packages are Available*

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Temperature Derating:

August, 2005 - Rev. 6

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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MARKING DIAGRAMS

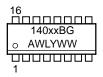


PDIP-16 P SUFFIX CASE 648



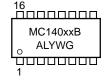


SOIC-16 D SUFFIX CASE 751B





SOEIAJ-16 F SUFFIX CASE 966



xx = Specific Device Code A = Assembly Location

 $\begin{array}{ll} \text{WL, L} &= \text{Wafer Lot} \\ \text{YY, Y} &= \text{Year} \\ \text{WW, W} &= \text{Work Week} \\ \text{G} &= \text{Pb-Free Indicator} \end{array}$

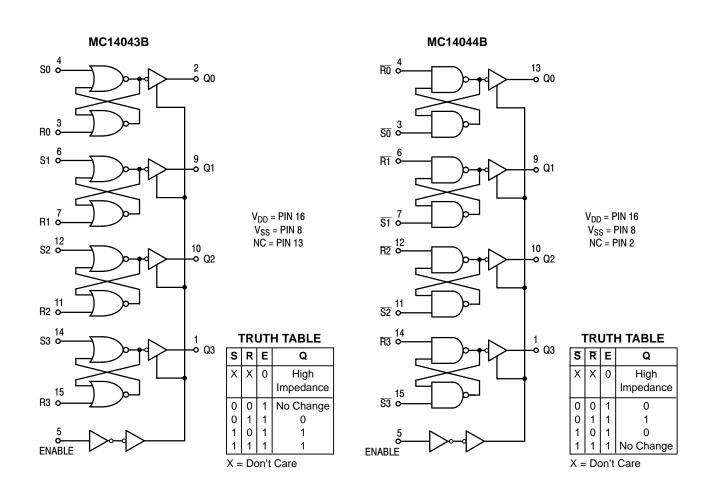
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

PIN ASSIGNMENT

	MC14043B			MC14044E	3
Q3 [1 ● 16	D V _{DD}	Q3 [1 ● 16	V _{DD}
Q0 [2 15	5	NC [2 15] S3
R0 [3 14	. □ S3	<u>so</u> [3 14] R3
S0 [4 13	B D NC	R0 [4 13] Q0
ΕŪ	5 12		Ε[5 12	R2
S1 [6 11] R2	R1 [6 11	<u> </u> <u>S2</u>
R1 [7 10) Q2	S1 [7 10	Q2
V _{SS} [8 9	<u>)</u>	V _{SS} [8 9	Q1

NC = NO CONNECTION



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

		.,	- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage "0" Level Vin = V _{DD} or 0	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD} "1" Leve	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" Level ($V_O = 4.5 \text{ or } 0.5 \text{ Vdc}$) ($V_O = 9.0 \text{ or } 1.0 \text{ Vdc}$) ($V_O = 13.5 \text{ or } 1.5 \text{ Vdc}$)	l V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
"1" Leve $(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ Source $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8		- 1.7 - 0.36 - 0.9 - 2.4		mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ Sin $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	k I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	I _{in}	15	-	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	-	_	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	- - -	1.0 2.0 4.0	- - -	0.002 0.004 0.006	1.0 2.0 4.0	- - -	30 60 120	μAdc
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs all buffers switching)	I _T	5.0 10 15			$I_{T} = (1$.58 μΑ/kHz) .15 μΑ/kHz) .73 μΑ/kHz)	f + I _{DD}			μAdc
Three–State Output Leakage Current	I _{TL}	15	_	± 0.1	_	± 0.0001	± 0.1	_	± 3.0	μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

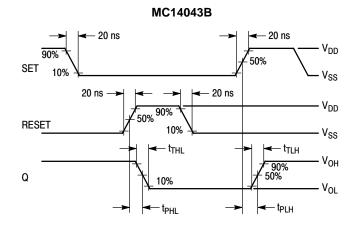
$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

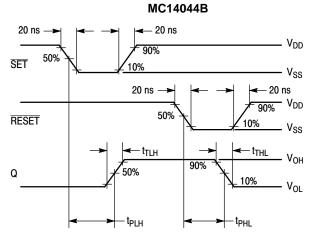
where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.004.

SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}$, $T_A = 25^{\circ}C$)

Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise Time	t _{TLH}					ns
$t_{TLH} = (1.35 \text{ ns/pF}) C_L + 32.5 \text{ ns}$		5.0	_	100	200	
$t_{TLH} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$		10	_	50	100	
$t_{TLH} = (0.40 \text{ ns/pF}) C_L + 20 \text{ ns}$		15	_	40	80	
Output Fall Time	t _{THL}					ns
$t_{THL} = (1.35 \text{ ns/pF}) C_L + 32.5 \text{ ns}$		5.0	_	100	200	
$t_{THL} = (0.60 \text{ ns/pF}) C_L + 20 \text{ ns}$		10	_	50	100	
$t_{THL} = (0.40 \text{ ns/pF}) C_L + 20 \text{ ns}$		15	_	40	80	
Propagation Delay Time	t _{PLH}					ns
$t_{PLH} = (0.90 \text{ ns/pF}) C_L + 130 \text{ ns}$		5.0	_	175	350	
$t_{PLH} = (0.36 \text{ ns/pF}) C_L + 57 \text{ ns}$		10	_	75	175	
$t_{PLH} = (0.26 \text{ ns/pF}) C_L + 47 \text{ ns}$		15	_	60	120	
$t_{PHL} = (0.90 \text{ ns/pF}) C_L + 130 \text{ ns}$	t _{PHL}	5.0	_	175	350	ns
$t_{PHL} = (0.90 \text{ ns/pF}) C_L + 57 \text{ ns}$		10	_	75	175	
$t_{PHL} = (0.26 \text{ ns/pF}) C_L + 47 \text{ ns}$		15	_	60	120	
Set, Set Pulse Width	t _W	5.0	200	80	_	ns
		10	100	40	_	
		15	70	30	-	
Reset, Reset Pulse Width	t _W	5.0	200	80	_	ns
		10	100	40	_	
		15	70	30	-	
Three-State Enable/Disable Delay	t _{PLZ} ,	5.0	_	150	300	ns
	t _{PHZ} ,	10	_	80	160	
	t _{PZL} ,	15	_	55	110	
	t _{PZH}					

AC WAVEFORMS



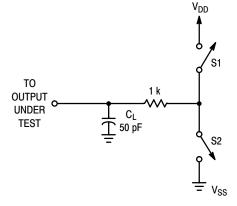


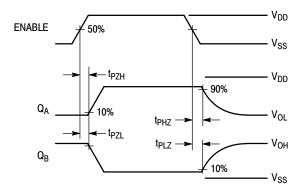
^{5.} The formulas given are for the typical characteristics only at 25°C.
6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

THREE-STATE ENABLE/DISABLE DELAYS

Set, Reset, Enable, and Switch Conditions for 3-State Tests

					MC14043B		MC14044B	
Test	Enable	S1	S2	Q	S	R	S	R
t _{PZH}		Open	Closed	Α	V _{DD}	V _{SS}	V _{SS}	V_{DD}
t _{PZL}		Closed	Open	В	V _{SS}	V_{DD}	V_{DD}	V_{SS}
t _{PHZ}	~	Open	Closed	Α	V_{DD}	V_{SS}	V_{SS}	V_{DD}
t _{PLZ}	~	Closed	Open	В	V _{SS}	V_{DD}	V_{DD}	V _{SS}





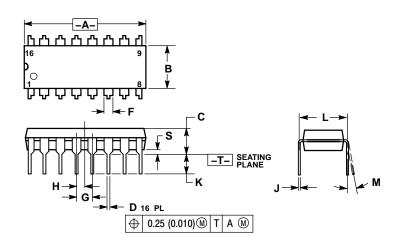
ORDERING INFORMATION

Device	Package	Shipping [†]
MC14043BCP	PDIP-16	500 Units / Rail
MC14043BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14043BD	SOIC-16	48 Units / Rail
MC14043BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14043BDR2	SOIC-16	2500 Units / Tape & Reel
MC14043BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14043BFEL	SOEIAJ-16	2000 Units / Tape & Reel
MC14044BCP	PDIP-16	500 Units / Rail
MC14044BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14044BD	SOIC-16	48 Units / Rail
MC14044BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14044BDR2	SOIC-16	2500 Units / Tape & Reel
MC14044BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

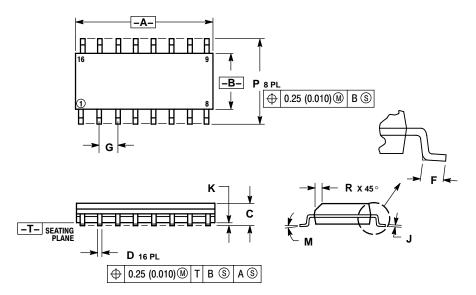
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIN	IMETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

SOIC-16 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751B-05 **ISSUE J**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) DED SIDE.

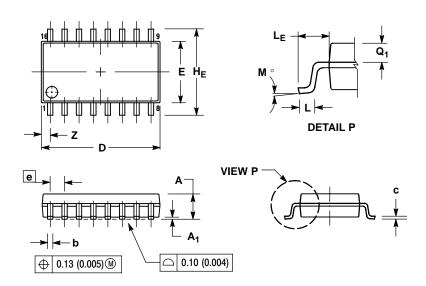
- PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE O**



NOTES:

- OTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q ₁	0.70	0.90	0.028	0.035
7		0.78		0.031

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